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*16/4586* (2013.01)(72) Inventor: **Xiqiang TIAN**, Beijing (CN)(21) Appl. No.: **17/999,914**(22) PCT Filed: **May 26, 2021**(86) PCT No.: **PCT/CN2021/095934**

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(57) **ABSTRACT**

A heating device includes a heating assembly. The heating assembly includes a ventilation structure configured to blow gas to an edge of a to-be-processed workpiece carried by the heating device. The heating device further includes a base arranged on a side of the heating assembly away from a heating surface of the heating assembly. A mounting space is formed between the base and the heating assembly. The heating device also includes a cooling mechanism arranged in the mounting space, located at a position corresponding to an edge area of the heating surface, and configured to cool the heating assembly.

